

PSR-2000

ECLIPSE

BY TAIYO



TECHNICAL DATA SHEET

TAIYO PSR-2000 ECLIPSE

Revised August 2013

LIQUID PHOTOIMAGEABLE SOLDER MASK

- ③ **Screen Print or Spray Application**
- ③ **A low-cost alternative to PSR-4000**
- ③ **RoHS Compliant**
- ③ **Halogen-Free**
- ③ **Compatible with Lead-Free Processing**



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TECHNICAL DATA SHEET

PROCESSING PARAMETERS FOR PSR-2000 ECLIPSE

PSR-2000 ECLIPSE is a two-component, alkaline developable LPI solder mask products for screen print and spray applications. The product is designed to be user friendly and flexible for today's quick turn / prototype manufacturers. **PSR-2000 ECLIPSE** offers a wide processing latitudes, with excellent coating properties and good resistance to alternate metal finishes such as ENIG and immersion Tin while maintaining dams of 2 mils or less. **PSR-2000 ECLIPSE** was designed to be the most environmentally friendly solder mask available. All Taiyo America products comply with the Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the Restriction of the use of certain Hazardous Substances (RoHS) in electrical and electronic equipment.

PSR-2000 ECLIPSE COMPONENTS:

PSR-2000 ECLIPSE / CA-25 ECLIPSE		
Mixing Ratio	80 parts	20 parts
Color	Green	White
Mixed Properties		
	Solids	82%
	Viscosity	200ps
	Specific Gravity	1.5

MIXING

PSR-2000 ECLIPSE is supplied in pre-measured containers with a mix ratio by weight of 80 parts, 0.8 kgs, **PSR-2000 ECLIPSE** and 20 parts, 0.2 kgs, **CA-25 ECLIPSE**. **PSR-2000 ECLIPSE** can be mixed a mechanical mixer at low speeds to minimize shear thinning for 10 – 15 minutes. The mixed pot life is 72 hours at room temperature.

PRE-CLEANING

Prior to solder mask application, the printed circuit board surface needs to be cleaned. Various cleaning methods include Pumice, Aluminum Oxide, Mechanical Brush, and Chemical Clean. All of these methods will provide a clean surface for the application of **PSR-2000 ECLIPSE**. Hold time after cleaning the printed circuit board should be held to a minimum to reduce the oxidation of the copper surfaces.



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- SCREEN PRINTING** Method: Single Sided and Double Sided Screening
- Screen Mesh: 29 – 43 threads/cm (74 – 110 tpi)
 - Screen Mesh Angle: 22.5° Bias
 - Screen Tension: 20 - 28 Newtons
 - Squeegee: 60 – 80 durometer
 - Squeegee Angle: 27 – 35°
 - Printing Mode: Flood / Print / Print
 - Flood Pressure: 20 – 30 psi
 - Printing Speed: 2.0 – 9.9 inches/sec
 - Printing Pressure: 75 – 100 psi
-

- TACK DRY CYCLE** The Tack Dry step is required to remove solvent from the solder mask film and produce a firm dry surface. The optimum dwell time and oven temperature will depend on oven type, oven loading, air circulation, exhaust rate, and ramp times. Excessive tack dry times and temperature will result in difficulty developing solder mask from through holes and a reduction in photo speed. Insufficient tack dry will result in artwork marking and/or sticking. Typical tack dry condition for **PSR-2000 ECLIPSE** is as followed:
- Oven Temperature: 68 - 82°C (155 - 180°C)
 - For Single-Sided (Batch Oven)
 - 1st Side: Dwell Time: 15 - 20 minutes
 - 2nd Side: Dwell Time: 20 - 40 minutes
 - For Double-Sided (Conveyorized or Batch Oven)
 - Dwell Time: 35 - 60 minutes
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- EXPOSURE** **PSR-2000 ECLIPSE** requires UV exposure to define solder mask dams and features. The spectral sensitivity of **PSR-2000 ECLIPSE** is in the area of 365 nm. Exposure times will vary by bulb type and age of the bulb. Below are guidelines for exposing **PSR-2000 ECLIPSE**.
- Exposure Unit: 7 kW or higher
 - Stouffer Step 21: Clear 10 minimum (on metal / under phototool)
 - Energy: 300 mJ / cm² minimum (under phototool)



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- DEVELOPMENT** **PSR-2000 ECLIPSE** is developed in an aqueous sodium or potassium carbonate solution. Developing can be done in either a horizontal or vertical machine.
- Solution: 1% by wt. Sodium Carbonate or 1.2% Potassium Carbonate
 - pH: 10.6 or greater
 - Temperature: 85 - 95°F (29 - 35°C)
 - Spray Pressure: 25 - 45 psi (1.7 – 3.1 bars)
 - Dwell Time in developing chamber: 45 - 120 seconds
 - Water rinse is needed to remove developer solution followed by a drying step
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PRE-CURE (OPTIONAL) This step may be required if the vias remain tented on both sides after developing due to the board design. The added drying cycle will prevent out-gassing of the vias. This phenomenon can cause the solder mask over the vias to peel or pop and may also exhibit a degree of oozing due to the entrapped solvent. The required drying cycle is 100 - 110°C for 40 to 60 minutes. An extended time may be required on the higher aspect ratio.

- FINAL CURE** **PSR-2000 ECLIPSE** requires a thermal cure to insure optimal final property performance. Thermal curing can be done in a batch oven or conveyORIZED oven.
- Temperature: 275 – 300°F (135 – 149°C)
 - Time at Temperature: 45 – 60 minutes
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For Process Optimization please contact your local Taiyo America Representative



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FINAL PROPERTIES FOR PSR-2000 ECLIPSE

IPC-SM-840D, Class H & T, Solder Mask Vendor Testing Requirements

TEST	SM-840 PARAGRAPH	REQUIREMENT	RESULT
Visual	3.3.1	Uniform in Appearance	Pass
Curing	3.2.5.1	Ref: 3.6.1.1, 3.7.1 and 3.7.2	Pass
Non-Nutrient	3.2.6	Does not contribute to biological growth	Pass
Pencil Hardness	3.5.1	Minimum "F"	Pass – 7H
Adhesion	3.5.2.1	Rigid – Cu, Ni, FR-4	Pass
Adhesion	3.5.2.6	Doubled Layered Solder Mask	Pass
Machinability	3.5.3	No Cracking or Tearing	Pass
Resistance to Solvents and Cleaning Agents	3.6.1.1	Table 3 Solvents	Pass
Hydrolytic Stability and Aging	3.6.2	No Change after 28 days of 95-99°C and 90-98% RH	Pass
Solderability	3.7.1	No Adverse Effect J-STD-003	Pass
Resistance to Solder	3.7.2	No Solder Sticking	Pass
Resistance to Solder	3.7.3	No Solder Sticking	Pass
Simulation of Lead Free Reflow	3.7.3.1	No Solder Sticking	Pass
Dielectric Strength	3.8.1	500 VDC / mil Minimum	TBD
Thermal Shock	3.9.3	No Blistering, Cracking or De-lamination	Pass

Specific Class "H" Requirements

TEST	SM-840 PARAGRAPH	REQUIREMENT	RESULT
Flammability	3.6.3.1	UL 94V-0	TBD
Insulation Resistance Before Soldering	3.8.2	5 x 10 ⁸ ohms minimum	TBD
After Soldering		5 x 10 ⁸ ohms minimum	TBD
Moisture & Insulation Resistance Before Soldering–In Chamber	3.9.1	5 x 10 ⁸ ohms minimum	TBD)
Before Soldering–Out of Chamber		5 x 10 ⁸ ohms minimum	TBD
After Soldering–In Chamber		5 x 10 ⁸ ohms minimum	TBD
After Soldering–Out of Chamber		5 x 10 ⁸ ohms minimum	TBD
Electrochemical Migration	3.9.2	>2.0 x 10 ⁶ ohms, no dendritic growth	TBD

Specific Class "T" Requirements

TEST	SM-840 PARAGRAPH	REQUIREMENT	RESULT
Flammability	3.6.3.2	Bellcore 0 ₂ Index – 28 minimum	TBD
Insulation Resistance Before Soldering	3.8.2	5 x 10 ⁸ ohms minimum	TBD
After Soldering		5 x 10 ⁸ ohms minimum	TBD



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FINAL PROPERTIES FOR PSR-2000 ECLIPSE

Specific Class “T” Requirements

TEST	SM-840 PARAGRAPH	REQUIREMENT	RESULT
Moisture & Insulation Resistance Before Soldering–In Chamber Before Soldering–Out of Chamber After Soldering–In Chamber After Soldering–Out of Chamber	3.9.1	5 x 10 ⁸ ohms minimum 5 x 10 ⁸ ohms minimum 5 x 10 ⁸ ohms minimum 5 x 10 ⁸ ohms minimum	TBD TBD TBD TBD
Electrochemical Migration	3.9.2	< 1 decade drop, no dendritic growth	Pass

Additional Tests / Results

TEST	REQUIREMENT	RESULT
CTI (Comparative Tracking Index)	ASTM-D-3638-07	TBD
Adhesion	GIP-008AA (TAIYO Internal Test Method) Cross-cut tape stripping test	100/100
Solder Heat Resistance	Solder float test: Rosin Flux 300°C/30sec., 1 cycle	Pass
Solvent Resistance	PGM-AC dipping, temp 20°C. / 20 min, Tape peeling test	Pass
Acid Resistance	10 vol% H ₂ SO ₄ , temp 20°C. / 20 min, Tape peeling test	Pass
Alkaline Resistance	10 wt% NaOH, temp 20°C. / 20 min, Tape peeling test	Pass
Dielectric Constant	JIS C C6481 values at 1MHz Humidify: 25-65°C (cycle), 90%RH, 7 days Measured: at room temperature	TBD
Dissipation Factor	JIS C C6481 values at 1MHz Humidify: 25-65°C (cycle), 90%RH, 7 days Measured: at room temperature	TBD
Electroless Ni/Au	TAIYO Internal Test Method Ni: 3 microns, Au: 0.03 microns	Pass
Outgassing Test; A 2 J/cm ² UV Cure was done after thermal cure	ASTM E-595-90; TML ≤ 1 % and CVCM ≤ 0.10%	T

Taiyo America, Inc. (TAIYO) warrants its products to be free from defects in materials and workmanship for the specified warranty period (**PSR-2000 ECLIPSE / CA-25 ECLIPSE Warranty period is 12 Months**) provided the customer has, at all times, stored the ink at a temperature of 68°F or less. TAIYO accepts no responsibility or liability for damages, whether direct, indirect, or consequential, resulting from failure in the performance of its products. If a TAIYO product is found to be defective in material or workmanship, its liability is limited to the purchase price of the product found to be defective. TAIYO MAKES NO OTHER WARRANTY, EXPRESS OR IMPLIED, AND MAKES NO WARRANTY OF MERCHANTABILITY OR OF FITNESS FOR ANY PARTICULAR PURPOSE. TAIYO'S obligation under this warranty shall not include any transportation charges or costs of installation or any liability for direct, indirect, or consequential damages or delay. If requested by TAIYO, products for which a warranty claim is made are to be returned transportation prepaid to TAIYO'S factory. Any improper use or any alteration of TAIYO'S product by the customer, as in TAIYO'S judgment affects the product materially and adversely, shall void this limited warranty.



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